

L4 ANSWER 1 OF 3 CAPLUS COPYRIGHT 2005 ACS on STN
 AN 1987:600602 CAPLUS
 DN 107:200602
 ED Entered STN: 27 Nov 1987
 TI Coating compositions
 IN Washiyama, Junichiro; Motoyama, Takuhiko
 PA Showa Denko K. K., Japan
 SO Jpn. Kokai Tokkyo Koho, 7 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 IC ICM C09D003-82
 ICA C08L083-04
 CC 42-10 (Coatings, Inks, and Related Products)
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 62124158	A2	19870605	JP 1985-264619	19851125 <--
PRAI	JP 1985-264619		19851125		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
JP 62124158	ICM	C09D003-82
	ICA	C08L083-04

AB Coating compns., heat- and chemical-resistant and useful on metals, ceramics, and plastics, contain ladder silicones and the siloxanes RO(SiR1R2O)mR3 [R, R3 = H, Me, Et; R1, R2 = (halogenated) Me, Et, Pr, Ph; m = 1-2000]. A blend of silsesquioxane (GR 100) 270, Ph2Si(OMe)2 30, and PhMe 700 g was coated on primed, sandblasted steel, dried at room temperature for 15 min, heated at 50° for 30 min and 90° for 30 min, cooled, recoated, and heated at 180° for 90 min. The 23-μ film showed no change after 1 h at 550°, after 50 h in 20% NaOH, concentrated H2SO4, AcOH, Me2CO, or PhMe at 50°, or after 1000-h salt spray testing.

ST siloxane blend coating; silsesquioxane coating chem resistance; heat resistance siloxane coating; steel coating siloxane blend

IT Coating materials
 (anticorrosive, silsesquioxane-siloxane blends as)

IT Coating materials
 (chemical- and heat-resistant, silsesquioxane-siloxane blends as)

IT 78-62-6, Dimethyldiethoxysilane 6843-66-9, Diphenyldimethoxysilane
 RL: USES (Uses)
 (in siloxane coatings, chemical- and heat-resistant)

RN 78-62-6
 RN 6843-66-9

L4 ANSWER 2 OF 3 WPIX COPYRIGHT 2005 THE THOMSON CORP on STN
 AN 1987-195216 [28] WPIX
 DNC C1987-081443

TI Coating compsn. with good heat and chemical resistance - contains a poly silicone resin and an organo siloxane cpd. e.g. di methyl di silanol.

DC A26 A82 G02 M13

PA (SHOW) SHOWA DENKO KK

CYC 1

PI JP 62124158 A 19870605 (198728)* 7 <--

ADT JP 62124158 A JP 1985-264619 19851125

PRAI JP 1985-264619 19851125

IC C08L083-04; C09D003-82

AB JP 62124158 A UPAB: 19930922

The compsn. contains (a) a silicone resin and (b) a organosiloxane cpd. of formula (I), where R1, R2 = methyl, ethyl, propyl or phenyl gp. opt. substd. with halogen; R3, R4 = H, methyl or ethyl gp.; n = 1-2000, pref. 1-200.

To prepare the compsn. 100 pts.weight of (a) and 0.1-30, pref. 1-20 pts.weight of (b) are dissolved in a solvent e.g. alcohol, ketone, aromatic hydrocarbon, ester and cellosolve.

ADVANTAGE - The compsn. for coating has good heat and chemical resistance and forms a coating film with no pin holes. It is used for coating the surfaces of metals, ceramics, plastics, etc.. (a) is shown by formula (II), where R5, R6 = methyl, ethyl butyl or phenyl gp. which may be substd. with halogen. n' = 3 to 200. (b) includes dimethyl dimethoxy (diethoxy)silane, dimethyl disilanol, diphenyl dimethoxy (diethoxy)silane, diphenyl silanol, methylphenyldimethoxy (diethoxy)silane, methylphenyl disilanol, etc..

0/0

FS CPI

FA AB

MC CPI: A06-A00E1; A08-D; A12-B01C; G02-A01A; M13-H05

L4 ANSWER 3 OF 3 JAPIO (C) 2005 JPO on STN

AN 1987-124158 JAPIO

TI COATING COMPOSITION

IN WASHIYAMA JUNICHIRO; MOTOYAMA TAKUHIKO

PA SHOWA DENKO KK

PI JP 62124158 A 19870605 Showa

AI JP 1985-264619 (JP60264619 Showa) 19851125

PRAI JP 1985-264619 19851125

SO PATENT ABSTRACTS OF JAPAN (CD-ROM), Unexamined Applications, Vol. 1987

IC ICM C09D003-82

ICA C08L083-04

AB PURPOSE: The titled composition having improved heat resistance and chemical resistance and good barrier properties to substrates free from pinhole, containing a ladder type silicone resin and a specific organosiloxane compound.

CONSTITUTION: The aimed composition containing (A) 100pts.weight ladder type silicone shown by formula I ($R_{5,6}$ are methyl, ethyl, butyl, phenyl, or halogen atom-substituted group thereof; n' is $3 \sim 200$) and (B) preferably $1 \sim 20$ pts. weight organosiloxane compound shown by formula II ($R_{1,2}$ are methyl, ethyl, propyl, phenyl or halogen-substituted group thereof; $R_{3,4}$ are H, methyl or ethyl; n is $1 \sim 2,000$).

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